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customized optoelectronics



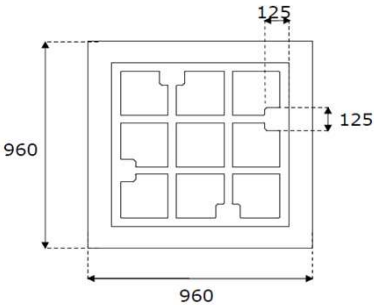
Product Data Sheet

LED Chip Infra Red

EOLC-740-21

Rev. 01 aus 2011

Radiation	Type	Electrodes
Infra red	DDH	N (cathode) up

	<p>typ. Dimensions (μm)</p> <p>typ. Thickness: 150 (± 25) μm</p> <p>cathode: gold alloy, 1.5 μm</p> <p>anode: gold alloy, 0.5 μm structured, 25% covered</p>
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Optical and Electrical Characteristics

$T_{\text{amb}} = 25^\circ\text{C}$, unless otherwise specified

Parameter	Test cond.	Symbol	Min	Typ	Max	Unit
Forward voltage	$I_F = 20\text{mA}$	V_F		1.5		V
Forward voltage	$I_F = 350\text{mA}$	V_F		1.9		V
Reverse voltage	$I_R = 100\mu\text{A}$	V_R	5			V
Radiant power*	$I_F = 20\text{mA}$	Φ_e	2.0	2.5		mW
Radiant power*	$I_F = 350\text{mA}$	Φ_e		35		mW
Peak wavelength	$I_F = 350\text{mA}$	λ_p	730	740	750	nm
Spectral bandwidth at 50%	$I_F = 350\text{mA}$	$\Delta\lambda_{0.5}$		30		nm
Switching time	$I_F = 20\text{mA}$	t_r, t_f		60		ns

*Measured on bare chip on TO18 header

Labeling

Type	Lot N°	Φ_e (typ) [mW]	V_F (typ) [V]	Qty.
EOLC-740-21				

Packing

Chips on adhesive film with wire bond side up